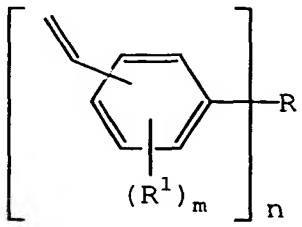
WHAT IS CLAIMED IS:

1. A low dielectric loss tangent resin composition containing a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further containing at least one member selected from a high polymer having a weight average molecular weight of not less than 5,000 and a filler.

2. The low dielectric loss tangent resin composition according to claim 1 wherein the high polymer is one having film-forming ability.

3. The low dielectric loss tangent resin composition according to claim 1 which contains a curing catalyst capable of polymerizing and crosslinking styrene groups or a polymerization inhibitor which can suppress the polymerization and crosslinking of styrene groups.

4. The low dielectric loss tangent resin

composition according to claim 1 wherein the high polymer contains at least one member selected from the group consisting of a homopolymer or copolymer of at least one monomer selected from butadiene, isoprene, styrene, ethylstyrene, divinylbenzene, N-vinylphenylmaleimide, acrylic ester and acrylonitrile, polyphenylene oxide which may have a substituent, polyolefin having a ring structure, polysiloxane and polyether imide.

5. The low dielectric loss tangent resin composition according to claim 1 wherein the filler contains at least one member selected from the group consisting of calcium carbonate, magnesium hydroxide, titanium oxide, silicon oxide, borosilicate glass, aluminium borate and carbon, each having an average particle diameter of 0.1-100 μm.

6. The low dielectric loss tangent resin composition according to claim 3 which contains 0.0005-10 parts by weight of the curing catalyst and 0.0005-5 parts by weight of the polymerization inhibitor, relative to 100 parts by weight of the whole resin component.

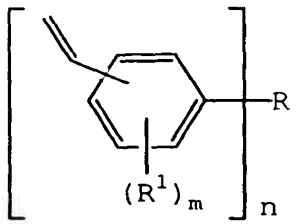
7. The low dielectric loss tangent resin composition according to claim 6 wherein the curing catalyst is an organic peroxide or a bisazide compound, and the polymerization inhibitor is a quinone or an aromatic diol.

8. A cured product obtained by curing the low

dielectric loss tangent resin composition according to claim 1.

9. The cured product according to claim 8 wherein the dielectric loss tangent after curing is not more than 0.002.

10. A curable film which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



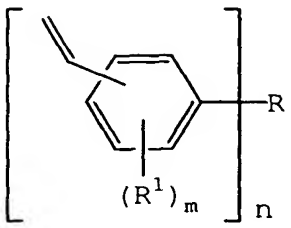
[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains a high polymer having film-forming ability.

11. The curable film according to claim 10 wherein a conductor layer has been formed on at least one surface of the curable film.

12. An electrical part having an insulator layer wherein the insulator layer contains a cured product of a low dielectric loss tangent resin composition which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a

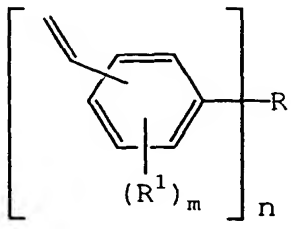
plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains at least one member selected from a high plolymer having a weight average molecular weight of not less than 5,000 and a filler.

13. A method for producing an electrical part having an insulator layer wherein the insulator layer is a curable film containing a low dielectric loss tangent resin composition which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a

substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains a high polymer having film-forming ability, and the curable film is lamination-bonded onto a conductor layer.